BGA Heat Sink (High Aspect Ratio Ext.) Standard Pin Fin





Description: 25.00 x 25.00 x 15.20 mm BGA Heat Sink (High Aspect Ratio Ext.) Standard Pin Fin



Heat Sink Type: Standard Pin Fin

Heat Sink Attachment: N/A
Equivalent Part Number: N/A

*Image above is for illustration purpose only.

Features & Benefits

- Excellent balance of low cost and high performance in an aluminum heat sink.
- Designed for semiconductor devices with omni-directional airflow requirements.
- 7 X 7 pin array
- Available with a variety of thermal adhesive tape options. Contact sales@qats.com for product configurations.

Thermal Performance

AIR VELOCITY		@200 LFM 1.0 M/S	@300 LFM 1.5 M/S	@400 LFM 2.0 M/S	@500 LFM 2.5 M/S	@600 LFM 3.0 M/S	@700 LFM 3.5 M/S	@800 LFM 4.0 M/S
THERMAL RESISTANCE	Unducted Flow	8 °C/W	N/A °C/W	N/A °C/W	N/A °C/W	N/A °C/W	N/A °C/W	N/A °C/W
	Ducted Flow	0	N/A	N/A	N/A	N/A	N/A	N/A

Product Detail

Schematic Image	Dimension A	Dimension B	Dimension C	Dimension D	TIM	Finish
nan	25.00 mm	25.00 mm	15.20 mm	N/A mm	NO TIM	Black Anodized
*Image above is for illustration purpose only.	 Dimension Thermal papplication ATS reserperforman ATS certifities 	ves the right to upda	eight from the bottor provided for referent ate or change its proc k assembly is RoHS	nce only. Actual perfo ducts without notice -6 and REACH comp	ormance may	vary by

For more information, to find a distributor or to place an order, please contact us at 781-769-2800 (North America), sales@qats.com or www.qats.com.

